

ML145502 ML145503 ML145505 **PCM Codec-Filter Mono-Circuit** 

Legacy Device: Motorola MC145502, MC145503, MC145505

The ML145502, ML145503, and ML145505 are all per channel PCM Codec–Filter mono–circuits. These devices perform the voice digitization and reconstruction as well as the band limiting and smoothing required for PCM systems. The ML145503 is a general purpose device that is offered in a 16-pin package. These are designed to operate in both synchronous and asynchronous applications and contain an on-chip precision reference voltage. The ML145505 is a synchronous device offered in a 16-pin DIP and wide body SOIC package intended for instrument use. The ML145502 is the full-featured device which presents all of the options of the chip. This device is packaged in a 22-pin DIP and a 28-pin chip carrier package

These devices are pin-for-pin replacements for Motorola's first generation of MC14400/01/02/03/05 PCM mono-circuits and are upwardly compatible with the MC14404/06/07 codecs and other industry standard codecs. They also maintain compatibility with Motorola's family of MC33120 and MC3419 SLIC products.

The ML1455xx family of PCM Codec–Filter mono–circuits utilizes CMOS due to its reliable low–power performance and proven capability for complex analog/digital VLSI functions.

#### ML145502

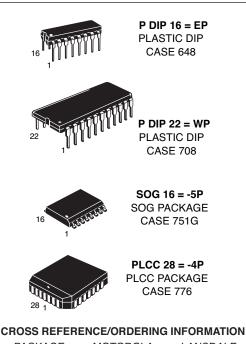
- 22 Pin and 28 Pin Packages
- Transmit Bandpass and Receive Low–Pass Filter On–Chip
- Pin Selectable Mu–Law/A–Law Companding with Corresponding
- On-Chip Precision Reference Voltage (3.15 V)
- Power Dissipation of 50 mW, Power–Down of 0.1 mW at  $\pm$ 5 V
- Automatic Prescaler Accepts 128 kHz, 1.536, 1.544, 2.048, and 2.56 MHz for Internal Sequencing
- Selectable Peak Overload Voltages (2.5, 3.15, 3.78 V)
- Access to the Inverting Input of the TxI Input Operational Amplifier
- Variable Data Clock Rates (64 kHz to 4.1 MHz)
- Complete Access to the Three Terminal Transmit Input Operational Amplifiers
- An External Precision Reference May Be Used

#### **ML145503**— Similar to the ML145502 Plus:

- 16–Pin Dip and SOIC 16 Packages
- Complete Access to the Three Terminal Transmit Input Operational **Amplifiers**

### ML145505 — Somewhat Similar To ML145503 Except:

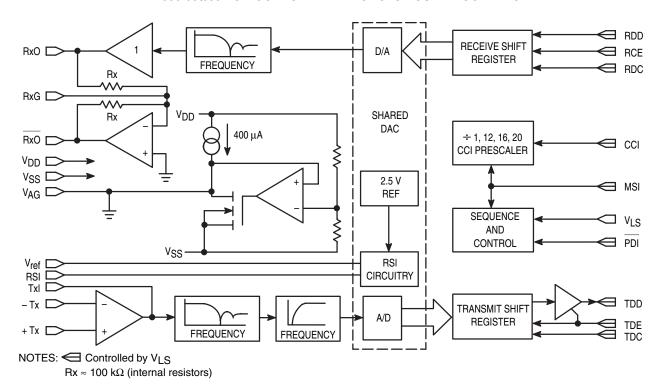
Common 64 kHz to 4.1 MHz Transmit/Receive Data Clock



PACKAGE	MOTOROLA	LANSDALE
P DIP 22	MC145502P	ML145502WP
PLCC 28	MC145502FN	ML145502-4P
P DIP 16	MC145503P	ML145503EP
SO 16W	MC145503DW	ML145503-5P
P DIP 16	MC145505P	ML145505EP
SO 16W	MC145505DW	ML145505-5P

Note: Lansdale lead free (Pb) product, as it becomes available, will be identified by a part number prefix change from ML to MLE.

#### ML145502/03/05 PCM CODEC-FILTER MONO-CIRCUIT BLOCK DIAGRAM

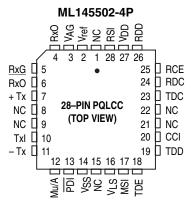


# PIN ASSIGNMENTS (DRAWINGS DO NOT REFLECT RELATIVE SIZE)

N	/IL145503	EP	•	N	/IL14550	5EF	
V <sub>AG</sub> [	1 ●	16	v <sub>DD</sub>	V <sub>AG</sub> [	1•	16	V <sub>DD</sub>
RxO [	2	15	RDD	RxO [	2	15	RDD
+ Tx [	3	14	RCE	+ Tx 🛚	3	14	RCE
Txl 🛭	4	13	RDC	ТхІ 🛚	4	13	DCLK
-тx [	5	12	TDC	– Tx 🛚	5	12	ССІ
Mu/A	6	11	D TDD	Mu/A	6	11	DDT [
PDI [	7	10	TDE	PDI [	7	10	TDE
V <sub>SS</sub> [	8	9	V <sub>LS</sub>	V <sub>SS</sub> [	8	9	□ v <sub>LS</sub>

	ML145	502W	Р
v <sub>ref</sub> [	1●	22	RSI
V <sub>AG</sub> [	2	21	V <sub>DD</sub>
RxO [	3	20	RDD
RxG [	4	19	RCE
RxO [	5	18	RDC
+ Tx [	6	17	TDC
Txl [	7	16	ССІ
– Tx [	8	15	D TDD
Mu/A	9	14	TDE
PDI [	10	13	изі 🛘
v <sub>SS</sub> [	11	12	V <sub>LS</sub>

Ŋ	/IL145503	3-5F	<b>.</b>	ľ	/IL145505	5-5F	
v <sub>ag</sub> [	1 ●	16	V <sub>DD</sub>	V <sub>AG</sub> [	1•	16	V <sub>DD</sub>
RxO [	2	15	RDD	RxO [	2	15	RDD
+ Tx [	3	14	RCE	+ Tx [	3	14	RCE
TxI 🛚	4	13	RDC	Txl [	4	13	DCL
– тх 🛚	5	12	TDC	– Tx [	5	12	ССІ
√lu/A [	6	11	DDT D	Mu/A	6	11	TDD
PDI [	7	10	] TDE	PDI [	7	10	TDE
v <sub>SS</sub> [	8	9	V <sub>LS</sub>	V <sub>SS</sub> [	8	9	V <sub>LS</sub>



NC = NO CONNECTION

# ABSOLUTE MAXIMUM RATINGS (Voltage Referenced to $V_{SS}$ )

Rating	Symbol	Value	Unit
DC Supply Voltage	V <sub>DD</sub> , V <sub>SS</sub>	- 0.5 to 13	V
Voltage, Any Pin to V <sub>SS</sub>	V	– 0.5 to V <sub>DD</sub> + 0.5	V
DC Drain Per Pin (Excluding V <sub>DD</sub> , V <sub>SS</sub> )	I	10	mA
Operating Temperature Range	TA	- 40 to + 85	°C
Storage Temperature Range	T <sub>stg</sub>	- 85 to + 150	°C

This device contains circuitry to protect against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit. For proper operation it is recommended that  $V_{in}$  and  $V_{out}$  be constrained to the range  $V_{SS}\!\leq\!(V_{in}$  or  $V_{out})$   $\!\leq\!V_{DD}.$  Unused inputs must always be tied to an

Unused inputs must always be tied to an appropriate logic voltage level (e.g., V<sub>SS</sub>, V<sub>DD</sub>, V<sub>LS</sub>, or V<sub>AG</sub>).

# **RECOMMENDED OPERATING CONDITIONS** $(T_A = -40 \text{ to} + 85^{\circ}\text{C})$

Characteristic	Min	Тур	Max	Unit	
DC Supply Voltage  Dual Supplies: VDD = -VSS, (VAG = VLS = 0 V)  Single Supply: VDD to VSS (VAG is an Output, VLS = VDD or VSS)	4.75	5.0	6.3	V	
ML145502, ML145503, ML145505 (Using Internal 3.15 V Reference				12.6	
ML145502 Using Internal 2.5 V Reference		7.0	_	12.6	
ML145502 Using Internal 3.78 V Reference	· ·			12.6	
ML145502 Using External 1.5 V Reference, Referenced to VAG		4.75	_	12.6	
Power Dissipation					mW
CMOS Logic Mode ( $V_{DD}$ to $V_{SS} = 10 \text{ V}$ , $V_{LS} = V_{DD}$ )	_	40	70		
TTL Logic Mode ( $V_{DD} = +5 \text{ V}$ , $V_{SS} = -5 \text{ V}$ , $V_{LS} = V_{AG} = 0 \text{ V}$ )		50	90		
Power Down Dissipation		_	0.1	1.0	mW
Frame Rate Transmit and Receive	7.5	8.0	8.5	kHz	
Data Rate		_	128	_	kHz
ML145503		_	1536	_	
Must Use One of These Frequencies, Relative to MSI Frequency of 8	kHz	_	1544	_	
		_	2048	_	
		_	2560	_	
Data Rate for ML145502, ML145505		64	_	4096	kHz
Full Scale Analog Input and Output Level					Vp
ML145503, ML145505		_	3.15	_	
ML145502 ( $V_{ref} = V_{SS}$ )	$RSI = V_{DD}$	_	3.78	_	
	$RSI = V_{SS}$	_	3.15	_	
MI 145500 Using an Estamol Reference Voltage Applied at V. Din	RSI = V <sub>AG</sub>	_ _	2.5	_	
ML145502 Using an External Reference Voltage Applied at V <sub>ref</sub> Pin	RSI = V <sub>DD</sub>	_	1.51 x V <sub>ref</sub>	_	
	$RSI = V_{SS}$ $RSI = V_{AG}$		1.26 x V <sub>ref</sub> V <sub>ref</sub>	_	
	rioi – VAG		, tet		

# **DIGITAL LEVELS** (VSS to VDD = 4.75 V to 12.6 V, $T_A = -40$ to $+85^{\circ}C$ )

Characteristic	Symbol	Min	Max	Unit
Input Voltage Levels (TDE, TDC, RCE, RDC, RDD, DC, MSI, CCI, PDI)				٧
CMOS Mode ( $V_{LS} = V_{DD}$ , $V_{SS}$ is Digital Ground) "0"	1 1	_	0.3 x V <sub>DD</sub>	
"1"	VIH	0.7 x V <sub>DD</sub>	l —	
TTL Mode ( $V_{LS} \le V_{DD} - 4.0 \text{ V}$ , $V_{LS}$ is Digital Ground) "0"	VIL		V <sub>LS</sub> + 0.8 V	
"1"	VIH	V <sub>LS</sub> + 2.0 V	_	
Output Current for TDD (Transmit Digital Data)				mA
CMOS Mode (V <sub>LS</sub> = V <sub>DD</sub> , V <sub>SS</sub> = 0 V and is Digital Ground)				
$(V_{DD} = 5 \text{ V}, V_{out} = 0.4 \text{ V})$	~-	1.0	-	
$(V_{DD} = 10 \text{ V}, V_{out} = 0.5 \text{ V})$		3.0	_	
$(V_{DD} = 5 \text{ V}, V_{out} = 4.5 \text{ V})$	J 0.1	- 1.0	_	
$(V_{DD} = 10 \text{ V}, V_{out} = 9.5 \text{ V})$		- 3.0	-	
TTL Mode ( $V_{LS} \le V_{DD} - 4.75 \text{ V}$ , $V_{LS} = 0 \text{ V}$ and is Digital Ground) ( $V_{OL} = 0.4 \text{ V}$ )	lOL	1.6	-	
(V <sub>OH</sub> = 2.4 V)	IOH	- 0.2	_	

# **ANALOG TRANSMISSION PERFORMANCE**

 $(V_{DD} = +5 \ V \pm 5\%, \ V_{SS} = -5 \ V \pm 5\%, \ V_{LS} = V_{AG} = 0 \ V, \ V_{ref} = RSI = V_{SS} \ (Internal \ 3.15 \ V \ Reference), \ 0 \ dBm0 = 1.546 \ Vrms = +6 \ dBm \ @ 600 \ \Omega, \ T_{A} = -40 \ to +85^{\circ}C, \ TDC = RDC = CC = 2.048 \ MHz, \ TDE = RCE = MSI = 8 \ kHz, \ Unless \ Otherwise \ Noted)$ 

	End-t	ind-to-End A/D		/D	D/A		
Characteristic	Min	Max	Min	Max	Min	Max	Unit
Absolute Gain (0 dBm0 @ 1.02 kHz, T <sub>A</sub> = 25°C, V <sub>DD</sub> = 5 V, V <sub>SS</sub> = - 5 V)	_	_	- 0.30	+ 0.30	- 0.30	+ 0.30	dB
Absolute Gain Variation with Temperature 0 to + 70°C	_	_	_	± 0.03	_	± 0.03	dB
Absolute Gain Variation with Temperature – 40 to +85°C	_	_	_	± 0.1	_	± 0.1	dB
Absolute Gain Variation with Power Supply (V <sub>DD</sub> = 5 V, V <sub>SS</sub> = - 5 V, 5%)	_	_	_	± 0.02	_	± 0.02	dB
Gain vs Level Tone (Relative to – 10 dBm0, 1.02 kHz) + 3 to – 40 dBm0 - 40 to – 50 dBm0 - 50 to – 55 dBm0	- 0.4 - 0.8 - 1.6	+ 0.4 + 0.8 + 1.6	- 0.2 - 0.4 - 0.8	+ 0.2 + 0.4 + 0.8	- 0.2 - 0.4 - 0.8	+ 0.2 + 0.4 + 0.8	dB
Gain vs Level Pseudo Noise (A–Law Relative to – 10 dBm0)  CCITT G.714  - 10 to – 40 dBm0  - 40 to – 50 dBm0  - 50 to – 55 dBm0	_ _ _	_ _ _	- 0.25 - 0.30 - 0.45	+ 0.25 + 0.30 + 0.45	- 0.25 - 0.30 - 0.45	+ 0.25 + 0.30 + 0.45	dB
Total Distortion – 1.02 kHz Tone (C–Message) 0 to – 30 dBm0 – 40 dBm0 – 45 dBm0	35 29 24	_ _ _	36 29 24	_ _ _	36 30 25	_ _ _	dBC
Total Distortion With Pseudo Noise (A–Law) — 3 dBm0 CCITT G.714 — 6 to – 27 dBm0 — 34 dBm0 — 40 dBm0 — 55 dBm0	27.5 35 33.1 28.2 13.2	_ _ _ _	28 35.5 33.5 28.5 13.5	_ _ _ _	28.5 36 34.2 30.0 15.0	_ _ _ _	dB
Idle Channel Noise (For End–End and A/D, See Note 1)  Mu–Law, C–Message Weighted  A–Law, Psophometric Weighted	_	15 - 69	_	15 - 69	_	9 - 78	dBrnC0 dBm0p
Frequency Response (Relative to 1.02 kHz @ 0 dBm0) 15 to 60 Hz 300 to 3000 Hz 3400 Hz 4000 Hz $ \begin{array}{c} 15 \text{ to 60 Hz} \\ 200 \text{ to 3000 Hz} \\ 200 \text{ Hz} \\ 200  $	 - 0.3 - 1.6 	- 23 + 0.3 0 - 28 - 60	 - 0.15 - 0.8  	- 23 + 0.15 0 - 14 - 32	 - 0.15 - 0.8  	0.15 + 0.15 0 - 14 - 30	dB
Inband Spurious (1.02 kHz @ 0 dBm0, Transmit and RxO) 300 to 3000 Hz	_	_	_	- 43	_	- 43	dBm0
Out-of-Band Spurious at RxO (300 - 3400 Hz @ 0 dBm0 In) 4600 to 7600 Hz 7600 to 8400 Hz 8400 to 100,000 Hz	_ _ _	- 30 - 40 - 30	_ _ _	_ _ _	_ _ _	- 30 - 40 - 30	dB
Idle Channel Noise Selective @ 8 kHz, Input = VAG, 30 Hz Bandwidth	_	- 70	_	_	_	<b>–</b> 70	dBm0
Absolute Delay @ 1600 Hz (TDC = 2.048 MHz, TDE = 8 kHz)		_	_	310	_	180	μs
Group Delay Referenced to 1600 Hz (TDC = 2048 kHz, TDE = 8 kHz)  500 to 600 Hz 600 to 800 Hz 800 to 1000 Hz 1000 to 1600 Hz 1600 to 2600 Hz 2600 to 2800 Hz 2800 to 3000 Hz	_ _ _ _ _		- - - - - -	200 140 70 40 75 110	- 40 - 40 - 30 - 20 		με
Crosstalk of 1020 Hz @ 0 dBm0 From A/D or D/A (Note 2)	_	_	_	<b>– 75</b>	_	- 80	dB
Intermodulation Distortion of Two Frequencies of Amplitudes – 4 to – 21 dBm0 from the Range 300 to 3400 Hz	_	_	_	- 41	_	- 41	dB

- 1. Extrapolated from a 1020 Hz @ 50 dBm0 distortion measurement to correct for encoder enhancement.
- 2. Selectively measured while the A/D is stimulated with 2667 Hz @ -50 dBm0.

# ANALOG ELECTRICAL CHARACTERISTICS (VDD = - VSS = 5 V to 6 V $\pm$ 5%, TA = - 40 to + 85°C)

$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	5   V <sub>SS</sub> + 1.0   0  V <sub>SS</sub> + 0.8  V <sub>SS</sub> + 1.5	± 0.01  10   < ± 30   70  1000  75	± 0.2	μA  MΩ  pF  mV  V  dB  kHz  dB  dBrnC0  pF
Input Capacitance $+Tx, -Tx$ Input Offset Voltage of Txl Op Amp  Input Common Mode Voltage Range $+Tx, -Tx$ $V_{ICR}$ Input Common Mode Rejection Ratio $+Tx, -Tx$ CMRR  Txl Unity Gain Bandwidth $+Tx, -Tx$ CMRR  Txl Unity Gain Bandwidth $+Tx, -Tx$ CMRR  Txl Open Loop Gain $+Tx, -Tx$ CMRR  Equivalent Input Noise (C-Message) Between $+Tx$ and $-Tx$ , at $Txl$ Output Load Capacitance for Txl Op Amp  Output Voltage Range Txl Op Amp, RxO or RxO $+Tx, -Tx$ CMRR $+$		<± 30 70 1000 75 20		pF mV V dB kHz dB
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		< ± 30 — 70 1000 75 — 20		mV V dB kHz dB dBmC0
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		 70 1000 75 20	_ _ _ _	V dB kHz dB dBrnC0
$ \begin{array}{ c c c c c } \hline \  \  & \  \  \  \  \  \  \  \  \  \  \$		1000 75 – 20	_ _ _ _	dB kHz dB dBrnC0
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		1000 75 – 20	_ _	kHz dB dBrnC0
$ \begin{array}{llllllllllllllllllllllllllllllllllll$		75 - 20	_ _	dB dBrnC0
Equivalent Input Noise (C–Message) Between +Tx and $-Tx$ , at Txl   Output Load Capacitance for Txl Op Amp   Output Voltage Range Txl Op Amp, RxO or RxO   RL = 10 k $\Omega$ to VAG   RL = 600 $\Omega$ to VAG   Output Current Txl, RxO, RxO   Output Impedance RxO, RxO*   Output Impedance RxO, RxO*   Output Load Capacitance for RxO and RxO*   Output dc Offset Voltage Referenced to VAG Pin   RxO   RxO*   Internal Gainsetting Resistors for RxG to RxO and RxO	0 V <sub>SS</sub> + 0.8	- 20	_	dBrnC0
Output Load Capacitance for Txl Op Amp  Output Voltage Range Txl Op Amp, RxO or RxO $R_L = 10 \ k\Omega \ \text{to VAG} $ $R_L = 600 \ \Omega \ \text{to VAG}$ Output Current Txl, RxO, RxO $V_{SS} + 1.5 \ \text{V} \leq V_{out} \leq V_{DD} - 1.5 \ \text{V}$ Output Impedance RxO, RxO* $0 \ \text{to } 3.4 \ \text{kHz}$ Output Load Capacitance for RxO and RxO* $0 \ \text{to Otherwise Acceptance}$ Output dc Offset Voltage Referenced to VAG Pin $\frac{RxO}{RxO^*}$ Internal Gainsetting Resistors for RxG to RxO and RxO	V <sub>SS</sub> + 0.8			
Output Voltage Range Txl Op Amp, RxO or RxO $R_L = 10 \text{ k}\Omega \text{ to V}_{AG} \\ R_L = 600 \Omega \text{ to V}_{AG} \\ \text{Output Current Txl, RxO, RxO} \qquad V_{SS} + 1.5 \text{ V} \leq \text{V}_{out} \leq \text{V}_{DD} - 1.5 \text{ V} \\ \text{Output Impedance RxO, RxO}^* \qquad 0 \text{ to } 3.4 \text{ kHz} \qquad Z_{out} \\ \text{Output Load Capacitance for RxO and RxO}^* \\ \text{Output dc Offset Voltage Referenced to V}_{AG} \text{Pin} \qquad \frac{\text{RxO}}{\text{RxO}^*} \\ \text{Internal Gainsetting Resistors for RxG to RxO and RxO} \\ \\ \text{Internal Gainsetting Resistors for RxG to RxO and RxO} \\ \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO and RxO}_{AB} \\ \text{Internal Gainsetting Resistors for RxG to RxO and RxO} \\ \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO and RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO and RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO and RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO and RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} \text{ to RxO}_{AB} \\ \text{Output Data of Capacitance for RxO}_{AB} $	V <sub>SS</sub> + 0.8	_	100	pF
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		_	İ	
Output Impedance RxO, RxO*  Output Load Capacitance for RxO and RxO*  Output dc Offset Voltage Referenced to VAG Pin  Internal Gainsetting Resistors for RxG to RxO and RxO		-	V <sub>DD</sub> – 1.0 V <sub>DD</sub> – 1.5	V
Output Load Capacitance for RxO and RxO*  Output dc Offset Voltage Referenced to VAG Pin  RxO RxO*  Internal Gainsetting Resistors for RxG to RxO and RxO	± 5.5	_	_	mA
Output dc Offset Voltage Referenced to V <sub>AG</sub> Pin  RxO RxO*  Internal Gainsetting Resistors for RxG to RxO and RxO	1 –	3	_	Ω
Internal Gainsetting Resistors for RxG to RxO and RxO	0	_	200	pF
-	_ _	_ _	± 100 ± 150	mV
External Reference Voltage Applied to V <sub>ref</sub> (Referenced to V <sub>AG</sub> )	62	100	225	kΩ
5 11 101 ( 7.G)	0.5	_	V <sub>DD</sub> – 1.0	V
V <sub>ref</sub> Input Current	<u> </u>	_	20	μА
V <sub>AG</sub> Output Bias Voltage	_	0.53 V <sub>DD</sub> + 0.47 V <sub>SS</sub>	_	V
VAG Output Current Source Sink	0.4 10.0	_ _	0.8 —	mA
Output Leakage Current During Power Down for the Txl Op Amp, VAG, RxO, and RxO	_	_	± 30	μА
Positive Power Supply Rejection Ratio, Transmit 0 – 100 kHz @ 250 mV, C–Message Weighting Receive	45 55	50 65	_ _	dBC
Negative Power Supply Rejection Ratio, Transmit 0 – 100 kHz @ 250 mV, C–Message Weighting Receive	50	55 60	_	dBC

<sup>\*</sup> Assumes that RxG is not connected for gain modifications to RxO.

# MODE CONTROL LOGIC (V\_SS to V\_DD = 4.75 V to 12.6 V, $T_A = -40$ to + $85^{\circ}$ C)

Characteristic		Min	Тур	Max	Unit
V <sub>LS</sub> Voltage for TTL Mode (TTL Logic Levels Referenced to	o V <sub>LS</sub> )	V <sub>SS</sub>	_	V <sub>DD</sub> – 4.0	V
$V_{LS}$ Voltage for CMOS Mode (CMOS Logic Levels of $V_{SS}$	to V <sub>DD</sub> )	V <sub>DD</sub> – 0.5	_	V <sub>DD</sub>	V
Mu/A Select Voltage Mu–Law Mode Sign Magnitude Mode A–Law Mode		V <sub>DD</sub> - 0.5 V <sub>AG</sub> - 0.5 V <sub>SS</sub>	_ _ _	V <sub>DD</sub> V <sub>AG</sub> + 0.5 V <sub>SS</sub> + 0.5	<b>&gt;</b>
RSI Voltage for Reference Select Input (ML145502)	3.78 V Mode 2.5 V Mode 3.15 V Mode	V <sub>DD</sub> - 0.5 V <sub>AG</sub> - 0.5 V <sub>SS</sub>	_ _ _	V <sub>DD</sub> V <sub>AG</sub> + 0.5 V <sub>SS</sub> + 0.5	V
V <sub>ref</sub> Voltage for Internal or External Reference (ML145502	Only) Internal Reference Mode External Reference Mode	V <sub>SS</sub> V <sub>AG</sub> + 0.5	<u> </u>	V <sub>SS</sub> + 0.5 V <sub>DD</sub> - 1.0	V
Analog Test Mode Frequency, MS = CCI (ML145502 Only) See Pin Description; Test Modes		_	128	_	kHz

# $\textbf{SWITCHING CHARACTERISTICS} \text{ (V}_{SS} \text{ to V}_{DD} = 9.5 \text{ V to } 12.6 \text{ V}, \text{ T}_{A} = -40 \text{ to } +85^{\circ}\text{C}, \text{ C}_{L} = 150 \text{ pF, CMOS or TTL Mode)}$

Characteristic	Symbol	Min	Тур	Max	Unit
Output Rise Time TDD Output Fall Time	tTLH tTHL	_	30 30	80 80	ns
Input Rise Time TDE, TDC, RCE, RDC, DC, MSI, CCI Input Fall Time	tTLH tTHL	_ _	_ _	4 4	μs
Pulse Width TDE Low, TDC, RCE, RDC, DC, MSI, CCI	t <sub>W</sub>	100	_	_	ns
DCLK Pulse Frequency (ML145502/05 Only) TDC, RDC, DC	fCL	64	_	4096	kHz
CCI Clock Pulse Frequency (MSI = 8 kHz) CCI is internally tied to TDC on the ML145503, therefore, the transmit data clock must be one of these frequencies. This pin will accept one of these discrete clock frequencies and will compensate to produce internal sequencing.	fCL1 fCL2 fCL3 fCL4 fCL5	_ _ _ _ _	128 1536 1544 2048 2560	_ _ _ _ _	kHz
Propagation Delay Time TDE Rising to TDD Low Impedance TTL CMOS	<sup>t</sup> P1		90 90	180 150	ns
TDE Falling to TDD High Impedance TTL CMOS	t <sub>P2</sub>	_	_	55 40	
TDC Rising Edge to TDD Data, During TDE High TTL CMOS	t <sub>P3</sub>	_ _	90 90	180 150	
TDE Rising Edge to TDD Data, During TDC High TTL CMOS	t <sub>P4</sub>	_	90 90	180 150	
TDC Falling Edge to TDE Rising Edge Setup Time	t <sub>su1</sub>	20	_	_	ns
TDE Rising Edge to TDC Falling Edge Setup Time	t <sub>su2</sub>	100	_	_	ns
TDE Falling Edge to TDC Rising Edge to Preserve the Next TDD Data	t <sub>su8</sub>	20	_	_	ns
RDC Falling Edge to RCE Rising Edge Setup Time	t <sub>su3</sub>	20	_	_	ns
RCE Rising Edge to RDC Falling Edge Setup Time	t <sub>su4</sub>	100	_	_	ns
RDD Valid to RDC Falling Edge Setup Time	t <sub>su5</sub>	60	_	_	ns
CCI Falling Edge to MSI Rising Edge Setup Time	t <sub>su6</sub>	20	_	_	ns
MSI Rising Edge to CCI Falling Edge Setup Time	t <sub>su7</sub>	100	_	_	ns
RDD Hold Time from RDC Falling Edge	th	100	_	_	ns
TDE, TDC, RCE, RDC, RDD, DC, MSI, CCI Input Capacitance		_	_	10	pF
TDE,TDC, RCE, RDC, RDD, DC, MSI, CCI Input Current		_	± 0.01	± 10	μА
TDD Capacitance During High Impedance (TDE Low)		_	12	15	pF
TDD Input Current During High Impedance (TDE Low)		_	± 0.1	± 10.0	μΑ

# **DEVICE DESCRIPTIONS**

A codec—filter is a device which is used for digitizing and reconstructing the human voice. These devices were developed primarily for the telephone network to facilitate voice switching and transmission. Once the voice is digitized, it may be switched by digital switching methods or transmitted long distance (T1, microwave, satellites, etc.) without degradation. The name codec is an acronym from "Coder" for the A/D used to digitize voice, and "Decoder" for the D/A used for reconstructing voice. A codec is a single device that does both the A/D and D/A conversions.

To digitize intelligible voice requires a signal to distortion of about 30 dB for a dynamic range of about 40 dB. This may be accomplished with a linear 13-bit A/D and D/A, but will far exceed the required signal to distortion at amplitudes greater than 40 dB below the peak amplitude. This excess performance is at the expense of data per sample. Two methods of data reduction are implemented by compressing the 13-bit linear scheme to companded 8-bit schemes. These companding schemes follow a segmented or "piecewise-linear" curve formatted as sign bit, three chord bits, and four stepbits. For a given chord, all 16 of the steps have the same voltage weighting. As the voltage of the analog input increases, the four step bits increment and carry to the three chord bits which increment. With the chord bits incremented, the step bits double their voltage weighting. This results in an effective resolution of 6-bits (sign + chord + four step bits) across a 42 dB dynamic range (7 chords above zero, by 6 dB per chord). There are two companding schemes used; Mu-255 Law specifically in North America, and A-Law specifically in Europe. These companding schemes are accepted worldwide. The tables show the linear quantization levels to PCM words for the two companding schemes.

In a sampling environment, Nyquist theory says that to properly sample a continuous signal, it must be sampled at a frequency higher than twice the signal's highest frequency component. Voice contains spectral energy above 3 kHz, but its absence is not detrimental to intelligibility. To reduce the digital data rate, which is proportional to the sampling rate, a sample rate of 8 kHz was adopted, consistent with a band-width of 3 kHz. This sampling requires a low–pass filter to limit the high frequency energy above 3 kHz from distorting the inband signal. The telephone line is also subject to 50/60 Hz power line coupling which must be attenuated from the signal by a high–pass filter before the A/D converter. The D/A process recon-

structs a staircase version of the desired inband signal which has spectral images of the in-band signal modulated about the sample frequency and its harmonics. These spectral images are called aliasing components which need to be attenuated to obtain the desired signal. The low—pass filter used to attenuate filter aliasing components is typically called a reconstruction or smoothing filter.

The ML1455XX series PCM Codec—Filters have the codec, both presampling and reconstruction filters, a precision voltage reference on chip, and require no external components. There are three distinct versions of the Lansdale ML1455XX Series.

#### ML145502

The ML145502 PCM Codec—Filter is the full feature 22—pin device. It is intended for use in applications requiring maximum flexibility. The ML145502 is intended for bit interleaved or byte interleaved applications with data clock frequencies which are nonstandard or time varying. One of the five standard frequencies (see ML145503 below) is applied to the CCI input, and the data clock inputs can be any frequency between 64 kHz and 4.096 MHz. The Vref pin allows for use of an external shared reference or selection of the internal reference. The RxG pin accommodates gain adjustments for the inverted analog output. All three pins of the input gain—setting operational amplifier are present, providing maximum flexibility for the analog interface.

#### ML145503

The ML145503 PCM Codec—Filter is intended for standard byte interleaved synchronous or asynchronous applications. TDC can be one of **five discrete frequencies**. These are 128 kHz (40 to 60% duty cycle), 1.536, 1.544, 2.048, or 2.56 MHz. (For other data clock frequencies, see ML145502 or ML145505.) The internal reference is set for 3.15 V peak full scale, and the full scale input level at Txl and output level at RxO is 6.3 V peak—to—peak. This is the + 3 dBm0 level of the PCM Codec—Filter. The +Tx and -Tx inputs provide maximum flexibility for analog interface. All other functions are described in the pin description.

#### ML145505

The ML145505 PCM Codec–Filter is intended for byte interleaved synchronous applications. The ML145505 has all the features of the ML145503 but internally connects TDC and RDC (see pin description) to the DC pin. One of the five standard frequencies (listed above) should be applied to CCI. The data clock input (DC) can be any frequency between 64 kHz and 4.096 MHz.

# PIN DESCRIPTIONS DIGITAL VI S

### Logic Level Select input and TTL Digital Ground

VLS controls the logic levels and digital ground reference for all digital inputs and the digital output. These devices can operate with logic levels from full supply (VSS to VDD) or with TTL logic levels using VLS as digital ground. For VLS = VDD, all I/O is full supply (VSS to VDD swing) with CMOS switch points. For VSS < VLS < (VDD – 4 V), all inputs and outputs are TTL compatible with VLS being the digital ground. The pins controlled by V are inputs MSI, CCI, TDE, TDC, RCE, RDC, RDD, PDI, and output TDD.

#### MSI

### **Master Synchronization Input**

MSI is used for determining the sample rate of the transmit side and as a time base for selecting the internal prescale divider for the convert clock input (CCI) pin. The MSI pin should be tied to an 8 kHz clock which may be a frame sync or system sync signal. MSI has no relation to transmit or receive data timing, except for determining the internal transmit strobe as described under the TDE pin description. MSI should be derived from the transmit timing in asynchronous applications. In many applications MSI can be tied to TDE. (MSI is tied internally to TDE in ML145503/05.)

### CCI Convert Clock Input

CCI is designed to accept five discrete clock frequencies. These are 128 kHz, 1.536 MHz, 1.544 MHz, 2.048 MHz, or 2.56 MHz. The frequency at this input is compared with MSI and prescale divided to produce the internal sequencing clock at 128 kHz (or 16 times the sampling rate). The duty cycle of CCI is dictated by the minimum pulse width except for 128 kHz, which is used directly for internal sequencing and must have a 40 to 60% duty cycle. In asynchronous applications, CCI should be derived from transmit timing. (CCI is tied internally to TDC in ML145503.)

#### **TDC**

#### **Transmit Data Clock Input**

TDC can be any frequency from 64 kHz to 4.096 MHz, and is often tied to CCI if the data rate is equal to one of the five discrete frequencies. This clock is the shift clock for the transmit shift register and its rising edges produce successive data bits at TDD. TDE should be derived from this clock. (TDC and RDC are tied together internally in the ML145505 and are called DC.) CCI is internally tied to TDC on the ML145503. Therefore, TDC must satisfy CCI timing requirements also.

#### TDF

#### **Transmit Data Enable Input**

TDE serves three major functions. The first TDE rising edge following an MSI rising edge generates the internal transmit strobe which initiates an A/D conversion. The internal transmit strobe also transfers a new PCM data word into the transmit shift register (sign bit first) ready to be output at TDD. The TDE pin is the high impedance control for the transmit digital data (TDD) output. As long as this pin is high, the TDD output stays low impedance. This pin also enables

the output shift register for clocking out the 8-bit serial PCM word. The logical AND of the TDE pin with the TDC pinclocks out a new data bit at TDD. TDE should be held high for eight consecutive TDC cycles to clock out a complete PCM word for byte interleaved applications. The transmit shift register feeds back on itself to allow multiple reads of the transmit data. If the PCM word is clocked out once per frame in a byte interleaved system, the MSI pin function is transparent and may be connected to TDE.

The TDE pin may be cycled during a PCM word for bit interleaved applications. TDE controls both the high impedance state of the TDD output and the internal shift clock. TDE must fall before TDC rises (t<sub>Su8</sub>) to ensure integrity of the next data bit. There must be at least two TDC falling edges between the last TDE rising edge of one frame and the first TDE rising edge of the next frame. MSI must be available separate from TDE for bit interleaved applications.

#### TDD

#### **Transmit Digital Data Output**

The output levels at this pin are controlled by the VLS pin. For VLS connected to VDD, the output levels are from VSS to VDD. For a voltage of VLS between VDD – 4 V and VSS, the output levels are TTL compatible with VLS being the digital ground supply. The TDD pin is a three–state output controlled by the TDE pin. The timing of this pin is controlled by TDC and TDE. When in TTL mode, this output may be made high–speed CMOS compatible using a pull–up resistor. The data format (Mu–Law, A–Law, or sign magnitude) is controlled by the Mu/A pin.

### RDC Receive Data Clock Input

RDC can be any frequency from 64 kHz to 4.096 MHz. This pin is often tied to the TDC pin for applications that can use a common clock for both transmit and receive data transfers. The receive shift register is controlled by the receive clock enable (RCE) pin to clock data into the receive digital data (RDD) pin on falling RDC edges. These three signals can be asynchronous with all other digital pins. The RDC input is internally tied to the TDC input on the ML145505 and called DC.

#### **RCE**

### Receive Clock Enable Input

The rising edge of RCE should identify the sign bit of a receive PCM word on RDD. The next falling edge of RDC, after a rising RCE, loads the first bit of the PCM word into the receive register. The next seven falling edges enter the remainder of the PCM word. On the ninth rising edge, the receive PCM word is transferred to the receive buffer register and the A/D sequence is interrupted to commence the decode process. In asynchronous applications with an 8 kHz transmit sample rate, the receive sample rate should be between 7.5 and 8.5 kHz. Two receive PCM words may be decoded and analog summed each transmit frame to allow on—chip conferencing. The two PCM words should be clocked in as two single PCM words, a minimum of 31.25 µs apart, with a receive data clock of 512 kHz or faster.

#### **RDD**

#### **Receive Digital Data Input**

RDD is the receive digital data input. The timing for this pin is controlled by RDC and RCE. The data format is determined by the Mu/A pin.

### Mu/A Select

This pin selects the companding law and the data format at TDD and RDD.

Mu/A = V<sub>DD</sub>; Mu–255 Companding D3 Data Format with Zero Code Suppress

Mu/A = VAG; Mu–255 Companding with Sign Magnitude Data Format

Mu/A = VSS; A–Law Companding with CCITT Data Format Bit Inversions

Code	Sign/ Magnitude		Mu-Law		l .	_aw ITT)
+ Full Scale	1111	1111	1000	0000	1010	1010
+ Zero	1000	0000	1111	1111	1101	0101
– Zero	0000	0000	0111	1111	0101	0101
– Full Scale	0111	1111	0000	0010	0010	1010

SIGN BIT	CH	HORD B	ITS		STEP	BITS	
0	1	2	3	4	5	6	7

NOTE: Starting from sign magnitude, to change format:

To Mu-Law -

MSB is unchanged (sign)

Invert remaining seven bits

If code is 0000 0000, change to 0000 0010 (for zero code suppression)

To A-Law -

MSB is unchanged (sign)

Invert odd numbered bits

Ignore zero code suppression

#### **PDI**

#### **Power Down Input**

The power down input disables the bias circuitry and gates off all clock inputs. This puts the  $V_{AG},$  Txl, RxO,  $\overline{\text{RxO}},$  and TDD outputs into a high–impedance state. The power dissipation is reduced to 0.1 mW when  $\overline{PDI}$  is a low logic level. The circuit operates normally with  $\overline{PDI} = V_{DD}$  or with a logic high as defined by connection at  $V_{LS}.$  TDD will not come out of high impedance for two MSI cycles after  $\overline{PDI}$  goes high.

#### **DCLK**

### **Data Clock Input**

In the ML145505, TDC and RDC are internally connected to DCLK.

#### **ANALOG**

### VAG

### **Analog Ground input/Output Pin**

VAG is the analog ground power supply input/output. All analog signals into and out of the device use this as their ground reference. Each version of the ML1455xx PCM Codec–Filter family can provide its own analog ground supply internally. The DC voltage of this internal supply is 6% positive of the midway between V<sub>DD</sub> and VSS. This supply can sink more than 8 mA but has a current source limited to 400 µA. The output of this supply is internally connected to the analog ground input of the part. The node where this supply and the analog ground are connected is brought out to the VAG pin. In symmetric dual supply systems ( $\pm 5$ ,  $\pm 6$ , etc.), VAG may be externally tied to the system analog ground supply. When RxO or RxO drive low impedance loads tied to VAG, a pull-up resistor to VDD will be required to boost the source current capability if VAG is not tied to the supply ground. All analog signals for the part are referenced to VAG, including noise; therefore, decoupling capacitors (0.1 μF) should be used from VDD to VAG and VSS to VAG.

### V<sub>ref</sub> Positive Voltage Reference Input (ML145502 Only)

The  $V_{ref}$  pin allows an external reference voltage to be used for the A/D and D/A conversions. If  $V_{ref}$  is tied to  $V_{SS}$ , the internal reference is selected. If  $V_{ref} > V_{AG}$ , then the external mode is selected and the voltage applied to  $V_{ref}$  is used for generating the internal converter reference voltage. In either internal or external reference mode, the actual voltage used for conversion is multiplied by the ratio selected by the RSI pin. The RSI pin circuitry is explained under its pin description below. Both the internal and external references are inverted within the PCM Codec–Filter for negative input voltages such that only one reference is required.

**External Mode** — In the external reference mode ( $V_{ref} > V_{AG}$ ), a 2.5 V reference like the MC1403 may be connected from  $V_{ref}$  to  $V_{AG}$ . A single external reference may be shared by tying together a number of  $V_{ref}$  pins and  $V_{AG}$  pins from different codec–filters. In special applications, the external reference voltage may be between 0.5 and 5 V. However, the reference voltage gain selection circuitry associated with RSI must be considered to arrive at the desired codec–filter gain.

**Internal Mode** — In the internal reference mode ( $V_{ref} = V_{SS}$ ), an internal 2.5 V reference supplies the reference voltage for the RSI circuitry. The  $V_{ref}$  pin is functionally connected to  $V_{SS}$  for the ML145503,and ML145505 pinouts.

#### **RSI**

### Reference Select Input (ML145502 Only)

The RSI input allows the selection of three different overload or full–scale A/D and D/A converter reference voltages independent of the internal or external reference mode. The RSI pin is a digital input that senses three different logic states:  $V_{SS},\,V_{AG},\,$  and  $V_{DD}.$  For RSI =  $V_{AG},\,$  the reference voltage is used directly for the converters. The internal reference is 2.5 V. For RSI =  $V_{SS},\,$  the reference voltage is multiplied by the ratio of 1.26, which results in an internal converter reference of 3.15 V. For RSI =  $V_{DD},\,$  the reference voltage is multiplied by 1.51, which results in an internal converter reference of 3.78 V. The device requires a minimum of 1.0 V of headroom between the internal converter reference to  $V_{DD}.\,$  VSS has this same absolute valued minimum, also measured from  $V_{AG}$  pin. The various modes of operation are summarized in Table 2. The RSI pin is functionally connected to  $V_{SS}$  for the ML145503, and ML145505 pinouts.

# RxO, RxO

### **Receive Analog Outputs**

These two complimentary outputs are generated from the output of the receive filter. They are equal in magnitude and out of phase. The maximum signal output of each is equal to the maximum peak—to—peak signal described with the reference. If a 3.15 V reference is used with RSI tied to  $V_{AG}$  and a + 3 dBm0 sine wave is decoded, the RxO output will be a 6.3 V peak—to—peak signal.  $\overline{RxO}$  will also have an inverted signal output of 6.3 V peak—to—peak. External loads may be connected from RxO to  $\overline{RxO}$  for a 6 dB push—pull signal gain or from either RxO or  $\overline{RxO}$  to  $V_{AG}$ . With a 3.15 V reference each output will drive 600  $\Omega$  to + 9 dBm. With RSI tied to  $V_{DD}$ , each output will drive 900  $\Omega$  to + 9 dBm.

#### RxG

### Receive Output Gain Adjust (ML145502 Only)

The purpose of the RxG pin is to allow external gain adjustment for the  $\overline{RxO}$  pin. If RxG is left open, then the output signal at RxO will be inverted and output at  $\overline{RxO}$ . Thus the push–pull gain to a load from RxO to RxO is two times the output level at RxO. If external resistors are applied from RxO to RxG (RI) and from RxG to RxO (RG), the gain of  $\overline{RxO}$  can be set differently from inverting unity. These resistors should be in the range of 10 k $\Omega$ . The RxO output level is unchanged by the resistors and the  $\overline{RxO}$  gain is approximately equal to minus RG/RI. The actual gain is determined by taking into account the internal resistors which will be in parallel to these external resistors. The internal resistors have a large tolerance, but they match each other very closely. This matching tends to minimize the effects of their tolerance on external gain configurations. The circuit for RxG and  $\overline{RxO}$  is shown in the block diagram.

#### Txl

#### **Transmit Analog Input**

TxI is the input to the transmit filter. It is also the output of the transmit gain amplifiers of the ML145502/03/05. The TxI input has an internal gain of 1.0, such that a +3 dBm0 signal at TxI corresponds to the peak converter reference voltage as described in the  $V_{\mbox{ref}}$  and RSI pin descriptions. For 3.15 V reference, the + 3 dBm0 input should be 6.3 V peak—to—peak.

### +Tx/-Tx

### Positive Tx Amplifier Input Negative Tx Amplifier Input

The Txl pin is the input to the transmit band–pass filter. If +Tx or -Tx is available, then there is an internal amplifier preceding the filter whose pins are +Tx, -Tx, and TxI. These pins allow access to the amplifier terminals to tailor the input gain with external resistors. The resistors should be in the range of  $10~k\Omega$ . If +Tx is not available, it is internally tied to VAG. If -Tx and +Tx are not available, the TxI is a unity gain high–impedance input.

#### **POWER SUPPLIES**

# **V**<sub>DD</sub>

# **Most Positive Power Supply**

V<sub>DD</sub> is typically 5 to 12 V.

### V<sub>SS</sub> Most Negative Power Supply

VSS is typically 10 to 12 V negative of VDD.

For a  $\pm 5$  V dual–supply system, the typical power supply configuration is V<sub>DD</sub> = + 5 V, V<sub>SS</sub> = - 5 V, V<sub>LS</sub> = 0 V (digital ground accommodating TTL logic levels), and V<sub>AG</sub> = 0 V being tied to system analog ground.

For single—supply applications, typical power supply configurations include:

 $V_{DD} = 10 \text{ V to } 12 \text{ V}$ 

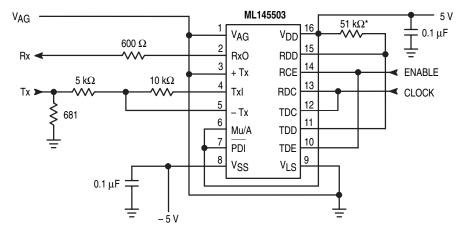
 $V_{SS} = 0 V$ 

VAG generates a mid supply voltage for referencing all analog signals.

 $V_{LS}$  controls the logic levels. This pin should be connected to  $V_{DD}$  for CMOS logic levels from  $V_{SS}$  to  $V_{DD}$ . This pin should be connected to digital ground for true TTL logic levels referenced to  $V_{LS}$ .

# **TESTING CONSIDERATIONS (ML145502 ONLY)**

An analog test mode is activated by connecting MSI and CCI to 128 kHz. In this mode, the input of the A/D (the output of the Tx filter) is available at the PDI pin. This input is direct coupled to the A/D side of the codec. The A/D is a differential design. This results in the gain of this input being effectively attenuated by half. If monitored with a high-impedance buffer, the output of the Tx low-pass filter can also be measured at the PDI pin. This test mode allows independent evaluation of the transmit low-pass filter and A/D side of the codec. The transmit and receive channels of these devices are tested with the codec-filter fully functional.



<sup>\*</sup> To define RDD when TDD is high Z.

Figure 1. Test Circuit

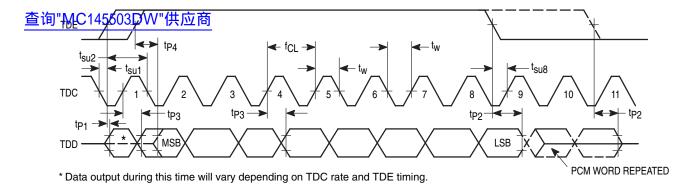
**Table 1. Options Available by Pin Selection** 

	-	-
RSI* Pin Level	V <sub>ref</sub> * Pin Level	Peak-to-Peak Overload Voltage (Txl, RxO)
V <sub>DD</sub>	V <sub>SS</sub>	7.56 V p–p
V <sub>DD</sub>	V <sub>AG</sub> + V <sub>EXT</sub>	(3.02 x V <sub>EXT</sub> ) V p-p
V <sub>AG</sub>	V <sub>SS</sub>	5 V p–p
V <sub>AG</sub>	V <sub>AG</sub> + V <sub>EXT</sub>	(2 x V <sub>EXT</sub> ) V p–p
V <sub>SS</sub>	V <sub>SS</sub>	6.3 V p–p
V <sub>SS</sub>	V <sub>AG</sub> + V <sub>EXT</sub>	(2.52 x V <sub>EXT</sub> ) V p−p

 $<sup>^{\</sup>star}$  On ML145503/05, RSI and  $V_{\mbox{ref}}$  tied internally to  $V_{\mbox{SS}}$  .

Table 2. Summary of Operation Conditions User Programmed Through Pins VDD, VAG, and VSS

Programmed Logic Level		RSI Peak Overload Voltage	V <sub>LS</sub>
V <sub>DD</sub>	Mu–Law Companding Curve and D3/D4 Digital Formats with Zero Code Suppress	3.78	CMOS Logic Levels
VAG	Mu–Law Companding Curve and Sign Magnitude Data Format	2.50	TTL Levels V <sub>AG</sub> Up
V <sub>SS</sub>	A–Law Companding Curve and CCITT Digital Format	3.15	TTL Levels VSS Up



**Figure 2. Transmit Timing Diagram** 

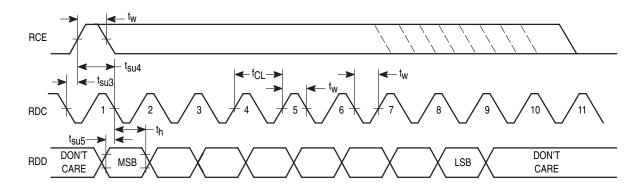


Figure 3. Receive Timing Diagram

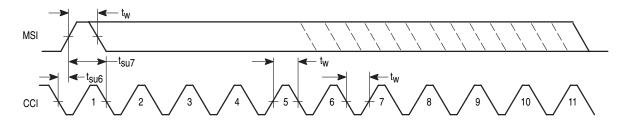


Figure 4. MSI/CCI Timing Diagram

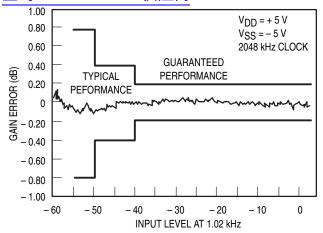


Figure 5. ML145502 Gain vs Level Mu-Law Transmit

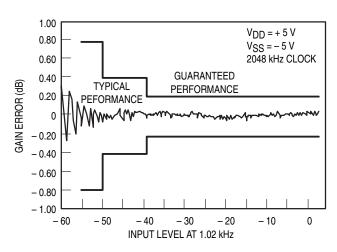


Figure 6. ML145502 Gain vs Level Mu-Law Receive

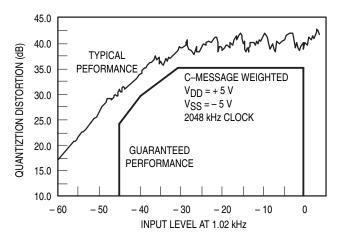


Figure 7. ML145502 Quantization Distortion Mu-Law Transmit

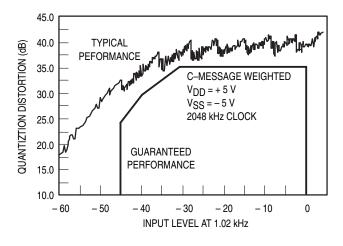


Figure 8. ML145502 Quantization Distortion Mu–Law Receive

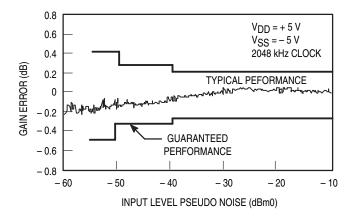


Figure 9. ML145502 Gain vs Level A-Law Transmit

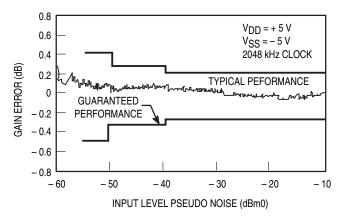


Figure 10. ML145502 Gain vs Level A-Law Receive

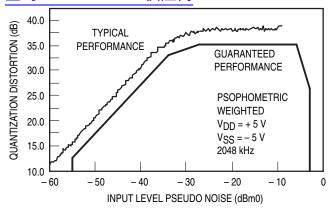


Figure 11. ML145502 Quantization Distortion A-Law Transmit

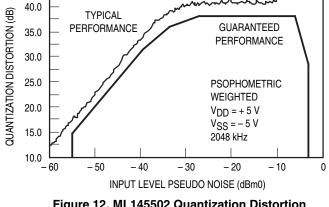


Figure 12. ML145502 Quantization Distortion A-Law Receive

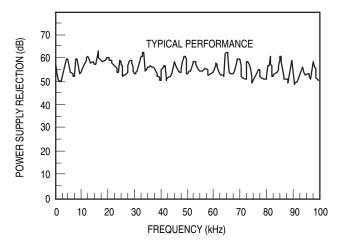


Figure 13. ML145502 Power Supply Rejection Ratio Positive Transmit VAC = 250 mVrms, C-Message Weighted

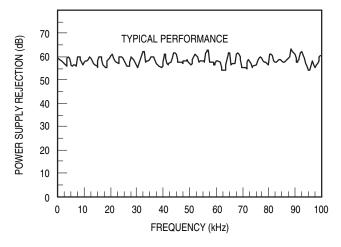


Figure 14. ML145502 Power Supply Rejection Ratio Negative Transmit VAC = 250 mVrms, C-Message Weighted

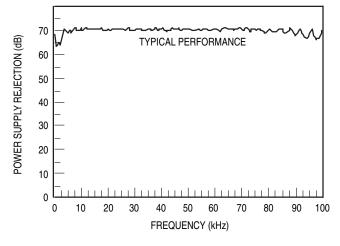


Figure 15. ML145502 Power Supply Rejection Ratio Positive Receive VAC = 250 mVrms, C-Message Weighted

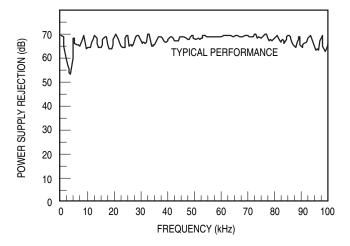


Figure 16. ML145502 Power Supply Rejection Ratio Negative Receive VAC = 250 mVrms, C-Message Weighted

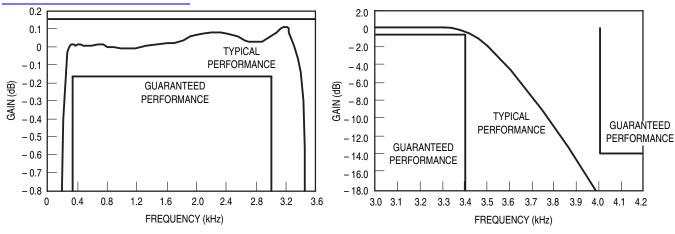


Figure 17. ML145502 Pass–Band Filter Response Transmit

Figure 18. ML145502 Low-Pass Filter Response Transmit

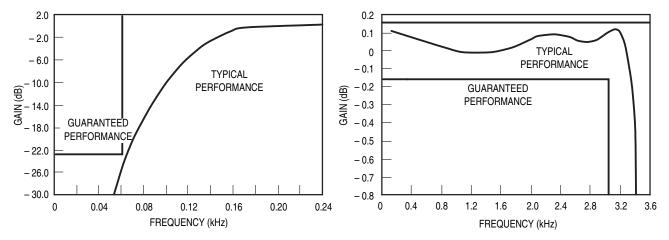


Figure 19. ML145502 High-Pass Filter Response Transmit

Figure 20. ML145502 Pass–Band Filter Response Receive

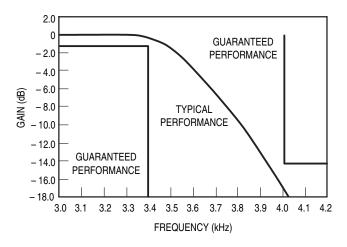
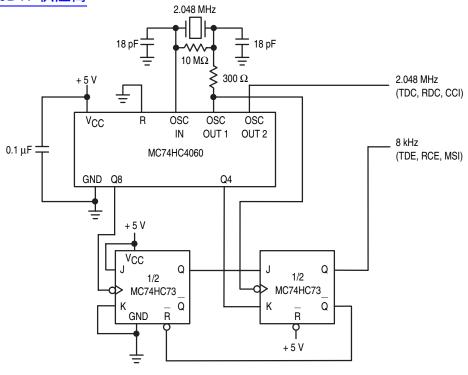


Figure 21. ML145502 Low-Pass Filter Response Receive



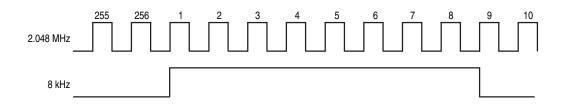
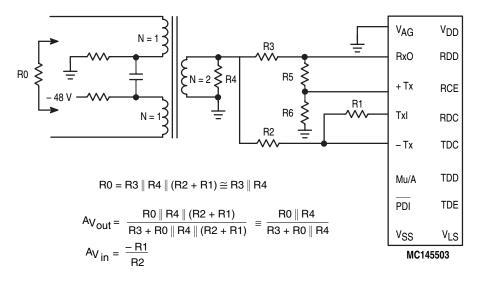


Figure 22. Simple Clock Circuit for Driving ML145502/03/05 Codec-Filters

#### 查询"MC145503DW"供应商 $V_{AG}$ $V_{DD}$ R0 RxO RDD + Tx RCE 10 kΩ TxI RDC 10 k $\Omega$ TDC – Tx TDD Mu/A PDI TDE $\text{V}_{\text{LS}}$ $V_{SS}$ MC145503

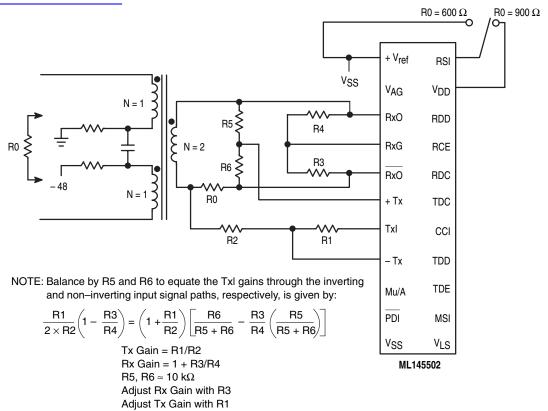
23a. Simplified Transformer Hybrid Using ML145503



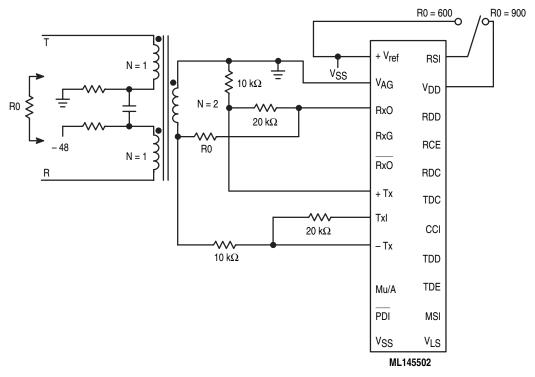
NOTE: Hybrid Balance by R5 and R6 to equate the RxO signal gain at Txl through the inverting and non-inverting signal paths.

# 23b. Universal Transformer Hybrid Using ML145503

Figure 23. Hybrid Interfaces to the ML145503 PCM Codec-Filter Mono-Circuit



24a. Universal Transformer Hybrid Using ML145502



24b. Single-Ended Hybrid Using ML145502

Figure 24. Hybrid Interfaces to the ML145502 PCM Codec-Filter Mono-Circuit

#### 查询"MC145503DW"供应商 0. RGE RDC 100 80 **TDC** 100 ۸LS ML145503 VAG 8 Ξ 0.1 R5 126 kΩ 10 kΩ 10 kΩ (A0) ⋛ (<del>A</del> R2 143 kΩ 0.47 0.47 R3 42.2 kΩ R1 30.1 kΩ R4 19.6 kΩ R7 270 kΩ 8 9 5 130 RSO HS0 VQB 뎞 Š HST 10 μF + 50 V -<del>|</del>|-|-爿 1 kΩ ္ပ RS EN Ш 品 BN TIP111 47 k 0.0047 0.0047 0.1 1N4002 19.6 kΩ 19.6 kΩ

75 Ω

≟

Figure 25. A Complete Single Party Channel Unit Using MC3419 SLIC and ML145503 PCM Mono-Circuit

RING.

75 Ω

0.0047 나

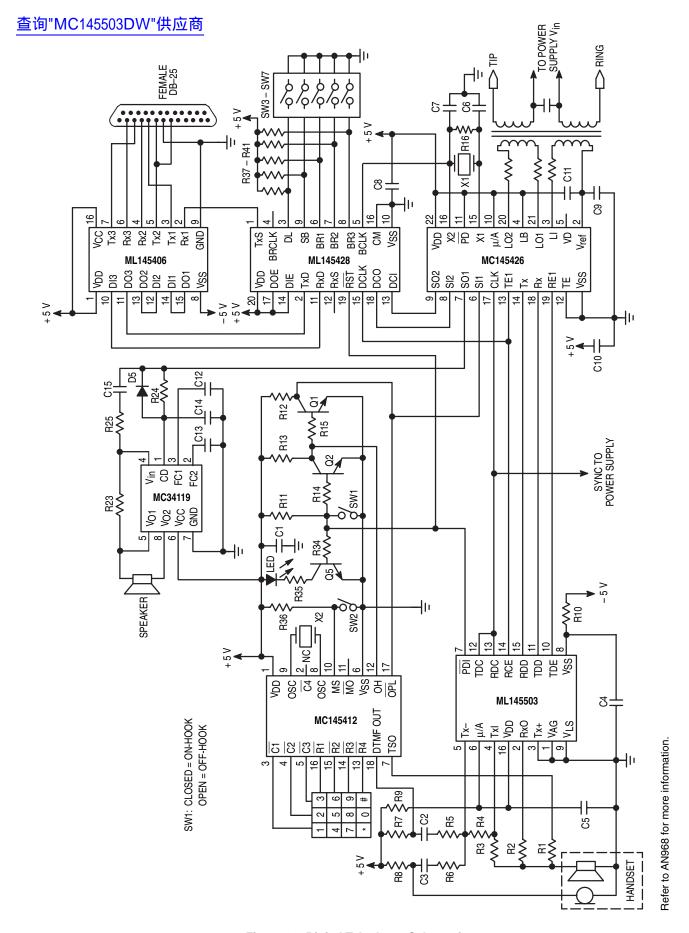


Figure 26. Digital Telephone Schematic

Table 3. Mu-Law Encode-Decode Characteristics

			Normalized Encode	Digital Code					Normalized			
Chord	Number	Step	Decision	1	2	3	4	5	6	7	8	Decode
Number	of Steps	Size	Levels	Sign	Chord	Chord	Chord	Step	Step	Step	Step	Levels
			– 8159 <b>–</b>	1	0	0	0	0	0	0	0	8031
8	16	256	7903 — :	'				 :				:
•	16	250	4319 <del>-</del>									
			– 4063 —	1	0	0	0	1	1	1	1	4191
7	16	128	2143 —					:				:
,	10	120		1	0	0	1	1	1	1	1	2079
	10		– 2015 – :					:				i i
6	16	64	1055 —	1	0	1	0	1	1	1	1	1023
			– 991 – :					:				:
5	16	32	511 —	1	0	1	1	1	1	1	1	495
			– 479 <b>–</b> :					:				:
4	16	16	239 —	1	1	0	0	1	1	1	1	231
			– 223 <i>–</i> :					• •				:
3	16	8	103 —	1	1	0	1	1	1	1	1	99
			– 95 <i>–</i> :					<u> </u>				:
2	16	4	35 —	1	1	1	0	1	1	1	1	33
			_ 31 —	'	ļ	ı				ı		
1	15	2	: 3 -					:				:
			- 1 -	1	1	1	1	1	1	1	0	2
	1	1	- 0 -	1	1	1	1	1	1	1	1	0
NOTEO												

<sup>1.</sup> Characteristics are symmetrical about analog zero with sign bit = 0 for negative analog values.
2. Digital code includes inversion of all magnitude bits.

# 查询"MC145503DW"供应商 Table 4. A-Law Encode-Decode Characteristics

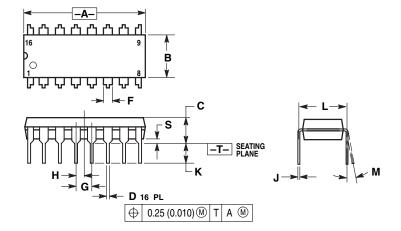
			Normalized Encode				Digital	Code				Normalized
Chord	Number	Step	Decision	1	2	3	4	5	6	7	8	Decode
Number	of Steps	Size	Levels	Sign	Chord	Chord	Chord	Step	Step	Step	Step	Levels
			4096 —									
				1	0	1	0	1	0	1	0	4032
7	16	128	3968 — :					:				:
			2176 —	1	0	1	0	0	1	0	1	2112
6	16	64	- 2048 - : 1088 -					:				:
0	סו	04	— 1024 —	1	0	1	1	0	1	0	1	1056
5	16	32	: : : : : : : : : : : : : : : : : : :					:				:
5	10	32	544 — 512 —	1	0	0	0	0	1	0	1	528
4	16	16	- 512 - : : 272 -					:				:
4	10	10		1	0	0	1	0	1	0	1	264
	10		:					:				:
3	16	8	136 —	1	1	1	0	0	1	0	1	132
2	16	4	- 128 - : 68 -					:				:
2	10	4		1	1	1	1	0	1	0	1	66
4	20		- 64 - : 2 -					:				:
1	32	2		1	1	0	1	0	1	0	1	1
			0 -									

<sup>1.</sup> Characteristics are symmetrical about analog zero with sign bit = 0 for negative analog values.

<sup>2.</sup> Digital code includes alternate bit inversion, as specified by CCITT.

#### **OUTLINE DIMENSIONS**

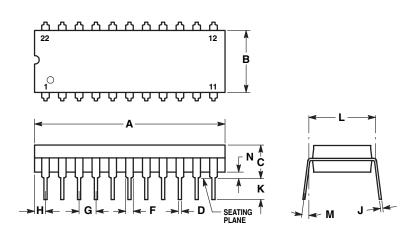
**P DIP 16 = EP** (ML145503EP, ML145505EP) **PLASTIC DIP CASE 648-08** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE MOLD FLASH. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

**P DIP 22 = WP** (ML145502WP) **PLASTIC DIP CASE 708-04** 



- NOTES:

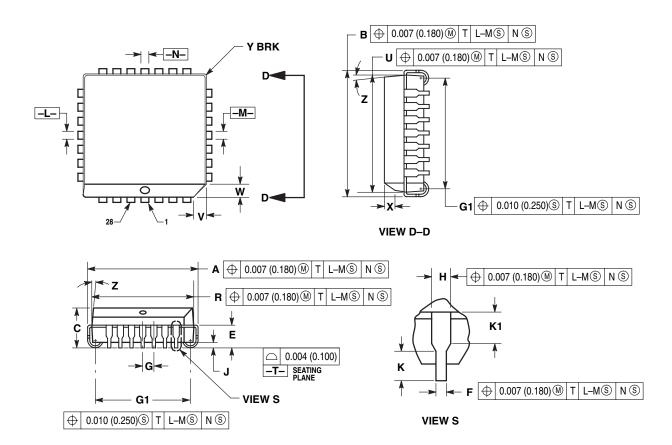
  1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25 (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.

  2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.

	MILLIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	27.56	28.32	1.085	1.115	
В	8.64	9.14	0.340	0.360	
С	3.94	5.08	0.155	0.200	
D	0.36	0.56	0.014	0.022	
F	1.27	1.78	0.050	0.070	
G	2.54	BSC	0.100 BSC		
Н	1.02	1.52	0.040	0.060	
J	0.20	0.38	0.008	0.015	
K	2.92	3.43	0.115	0.135	
L	10.16 BSC		0.400 BSC		
M	0°	15°	0°	15°	
N	0.51	1.02	0.020	0.040	

# **OUTLINE DIMENSIONS**

PLCC 28 = -4P (ML145502-4P) PLCC PACKAGE CASE 776-02



- OLES.

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION 61, TRUE POSITION TO BE MEDICAL PROPERTY AND ADMINISTRATION FOR THE PROPERTY AND ADMINISTRA
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
   DIMENSIONS R AND U DO NOT INCLUDE
- DIMENSIONS R AND U DO NOT INCLUDE
   MOLD FLASH. ALLOWABLE MOLD FLASH IS
   0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI Y14-5M, 1952.

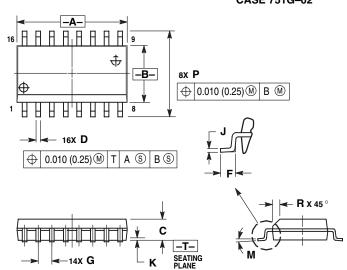
  S. CONTROLLING DIMENSION: INCH.

  THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U A RE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- 7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.485	0.495	12.32	12.57
В	0.485	0.495	12.32	12.57
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2 °	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040		1.02	

# **OUTLINE DIMENSIONS**

SO 16 = -5P(ML145503-5P, ML145505-5P) **SOG PACKAGE** CASE 751G-02



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD
- PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	10.15	10.45	0.400	0.411	
В	7.40	7.60	0.292	0.299	
C	2.35	2.65	0.093	0.104	
D	0.35	0.49	0.014	0.019	
F	0.50	0.90	0.020	0.035	
G	1.27	BSC	0.050 BSC		
J	0.25	0.32	0.010	0.012	
K	0.10	0.25	0.004	0.009	
M	0 °	7 °	0 °	7 °	
Р	10.05	10.55	0.395	0.415	
R	0.25	0.75	0.010	0.029	

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